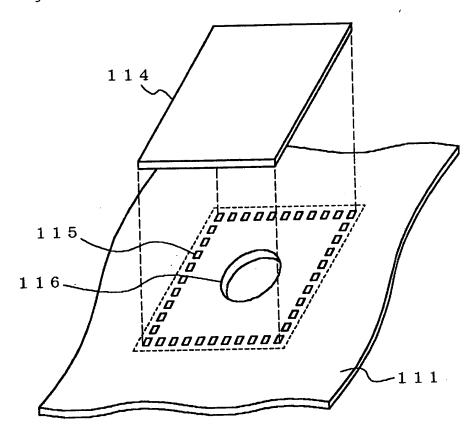
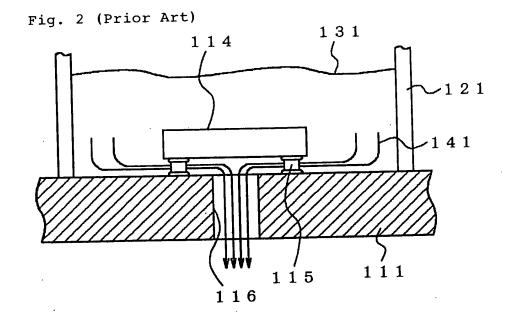
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Fig. 1 (Prior Art)





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Fig. 3a

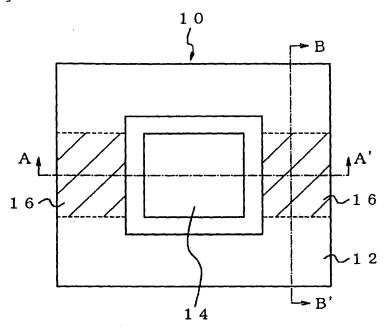


Fig. 3b

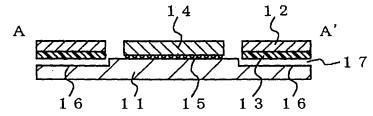
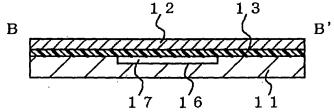
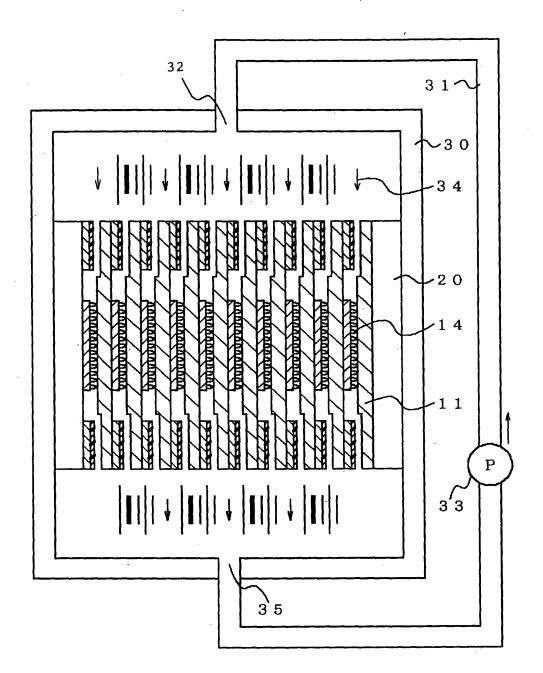


Fig. 3c



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Fig. 4



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Fig. 5

Arranging flip chip

Reflowing

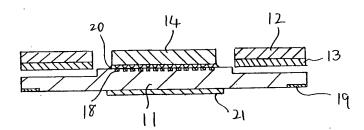
Cleaning

Injecting underfill resin

Cureing resin

Appling heat sink

Fig. 6



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Fig. 7a

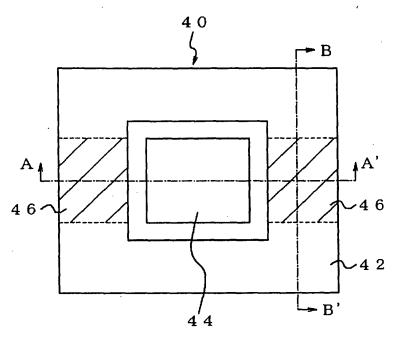


Fig. 7b

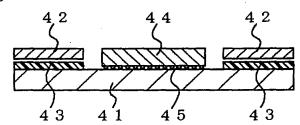
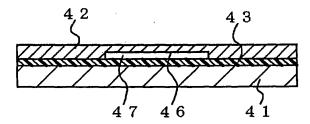


Fig. 7c



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Fig. 8a

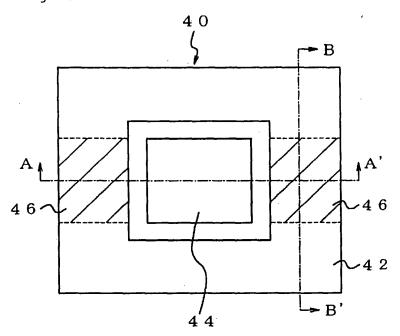


Fig. 8b

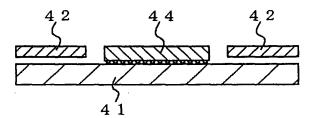


Fig. 8c

